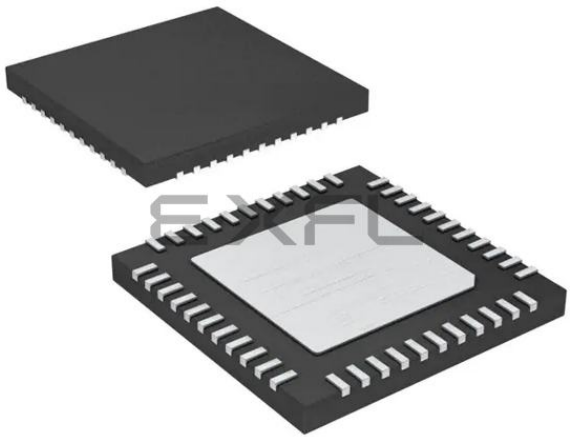
Microchip Technology - PIC24F16KA304T-I/ML Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	39
Program Memory Size	16KB (5.5K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 16x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24f16ka304t-i-ml

TABLE 1-2: DEVICE FEATURES FOR THE PIC24F32KA304 FAMILY

Features	PIC24F16KA301	PIC24F32KA301	PIC24F16KA302	PIC24F32KA302	PIC16F16KA304	PIC24F32KA304
Operating Frequency	DC – 32 MHz					
Program Memory (bytes)	16K	32K	16K	32K	16K	32K
Program Memory (instructions)	5632	11264	5632	11264	5632	11264
Data Memory (bytes)	2048					
Data EEPROM Memory (bytes)	512					
Interrupt Sources (soft vectors/ NMI traps)	30 (26/4)					
I/O Ports	PORTA<6:0>, PORTB<15:12, 9:7, 4, 2:0>		PORTA<7:0>, PORTB<15:0>		PORTA<11:0>, PORTB<15:0>, PORTC<9:0>	
Total I/O Pins	18		24		39	
Timers: Total Number (16-bit)	5					
32-Bit (from paired 16-bit timers)	2					
Input Capture Channels	3					
Output Compare/PWM Channels	3					
Input Change Notification Interrupt	17		23		38	
Serial Communications: UART SPI (3-wire/4-wire)	2					
I^2C™	2					
12-Bit Analog-to-Digital Module (input channels)	12		13		16	
Analog Comparators	3					
Resets (and delays)	POR, BOR, RESET Instruction, $\overline{MCLR}$, WDT, Illegal Opcode, REPEAT Instruction, Hardware Traps, Configuration Word Mismatch (PWRT, OST, PLL Lock)					
Instruction Set	76 Base Instructions, Multiple Addressing Mode Variations					
Packages	20-Pin PDIP/SSOP/SOIC		28-Pin SPDIP/SSOP/SOIC/QFN		44-Pin QFN/TQFP 48-Pin UQFN	

3.2 CPU Control Registers

REGISTER 3-1: SR: ALU STATUS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0, HSC
—	—	—	—	—	—	—	DC
bit 15							bit 8

R/W-0, HSC(1)	R/W-0, HSC(1)	R/W-0, HSC(1)	R-0, HSC	R/W-0, HSC	R/W-0, HSC	R/W-0, HSC	R/W-0, HSC
IPL2(2)	IPL1(2)	IPL0(2)	RA	N	OV	Z	C
bit 7							bit 0

Legend:	HSC = Hardware Settable/Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as '0'

bit 8 **DC:** ALU Half Carry/Borrow bit
1 = A carry-out from the 4th low-order bit (for byte-sized data) or 8th low-order bit (for word-sized data) of the result occurred
0 = No carry-out from the 4th or 8th low-order bit of the result has occurred

bit 7-5 **IPL<2:0>:** CPU Interrupt Priority Level Status bits(1,2)
111 = CPU Interrupt Priority Level is 7 (15); user interrupts are disabled
110 = CPU Interrupt Priority Level is 6 (14)
101 = CPU Interrupt Priority Level is 5 (13)
100 = CPU Interrupt Priority Level is 4 (12)
011 = CPU Interrupt Priority Level is 3 (11)
010 = CPU Interrupt Priority Level is 2 (10)
001 = CPU Interrupt Priority Level is 1 (9)
000 = CPU Interrupt Priority Level is 0 (8)

bit 4 **RA:** REPEAT Loop Active bit
1 = REPEAT loop in progress
0 = REPEAT loop not in progress

bit 3 **N:** ALU Negative bit
1 = Result was negative
0 = Result was non-negative (zero or positive)

bit 2 **OV:** ALU Overflow bit
1 = Overflow occurred for signed (2's complement) arithmetic in this arithmetic operation
0 = No overflow has occurred

bit 1 **Z:** ALU Zero bit
1 = An operation, which effects the Z bit, has set it at some time in the past
0 = The most recent operation, which effects the Z bit, has cleared it (i.e., a non-zero result)

bit 0 **C:** ALU Carry/$\overline{\text{Borrow}}$ bit
1 = A carry-out from the Most Significant bit (MSb) of the result occurred
0 = No carry-out from the Most Significant bit (MSb) of the result occurred

Note 1: The IPLx Status bits are read-only when NSTDIS (INTCON1<15>) = 1.
2: The IPL<2:0> Status bits are concatenated with the IPL3 bit (CORCON<3>) to form the CPU Interrupt Priority Level (IPL). The value in parentheses indicates the IPL when IPL3 = 1.

5.0 FLASH PROGRAM MEMORY

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on Flash programming, refer to the *"PIC24F Family Reference Manual"*, **Section 4. "Program Memory"** (DS39715).

The PIC24FV32KA304 family of devices contains internal Flash program memory for storing and executing application code. The memory is readable, writable and erasable when operating with VDD over 1.8V.

Flash memory can be programmed in three ways:

- In-Circuit Serial Programming™ (ICSP™)
- Run-Time Self Programming (RTSP)
- Enhanced In-Circuit Serial Programming (Enhanced ICSP)

ICSP allows a PIC24FV32KA304 device to be serially programmed while in the end application circuit. This is simply done with two lines for the programming clock and programming data (which are named PGECx and PGEDx, respectively), and three other lines for power (VDD), ground (VSS) and Master Clear/Program mode Entry Voltage ($\overline{MCLR}$/VPP). This allows customers to manufacture boards with unprogrammed devices and then program the microcontroller just before shipping the product. This also allows the most recent firmware or custom firmware to be programmed.

Run-Time Self Programming (RTSP) is accomplished using TBLRD (Table Read) and TBLWT (Table Write) instructions. With RTSP, the user may write program memory data in blocks of 32 instructions (96 bytes) at a time, and erase program memory in blocks of 32, 64 and 128 instructions (96,192 and 384 bytes) at a time.

The NVMOP<1:0> (NVMCON<1:0>) bits decide the erase block size.

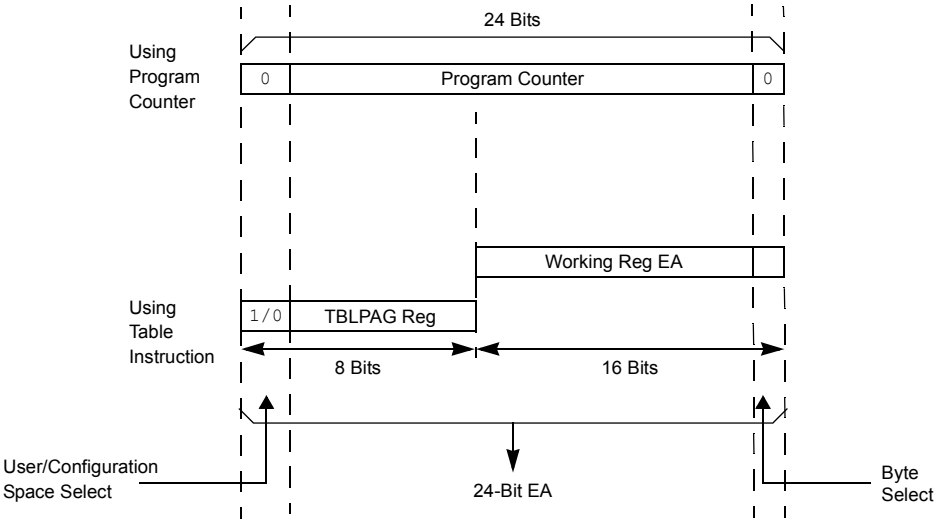
5.1 Table Instructions and Flash Programming

Regardless of the method used, Flash memory programming is done with the table read and write instructions. These allow direct read and write access to the program memory space from the data memory while the device is in normal operating mode. The 24-bit target address in the program memory is formed using the TBLPAG<7:0> bits and the Effective Address (EA) from a W register, specified in the table instruction, as depicted in Figure 5-1.

The TBLRDL and the TBLWTL instructions are used to read or write to bits<15:0> of program memory. TBLRDL and TBLWTL can access program memory in both Word and Byte modes.

The TBLRDH and TBLWTH instructions are used to read or write to bits<23:16> of program memory. TBLRDH and TBLWTH can also access program memory in Word or Byte mode.

FIGURE 5-1: ADDRESSING FOR TABLE REGISTERS



5.5.1 PROGRAMMING ALGORITHM FOR FLASH PROGRAM MEMORY

The user can program one row of Flash program memory at a time by erasing the programmable row. The general process is as follows:

1. Read a row of program memory (32 instructions) and store in data RAM.
2. Update the program data in RAM with the desired new data.
3. Erase a row (see Example 5-1):
   a) Set the NVMOPx bits (NVMCON<5:0>) to '011000' to configure for row erase. Set the ERASE (NVMCON<6>) and WREN (NVMCON<14>) bits.
   b) Write the starting address of the block to be erased into the TBLPAG and W registers.
   c) Write 55h to NVMKEY.
   d) Write AAh to NVMKEY.
   e) Set the WR bit (NVMCON<15>). The erase cycle begins and the CPU stalls for the duration of the erase cycle. When the erase is done, the WR bit is cleared automatically.
4. Write the first 32 instructions from data RAM into the program memory buffers (see Example 5-1).
5. Write the program block to Flash memory:
   a) Set the NVMOPx bits to '011000' to configure for row programming. Clear the ERASE bit and set the WREN bit.
   b) Write 55h to NVMKEY.
   c) Write AAh to NVMKEY.
   d) Set the WR bit. The programming cycle begins and the CPU stalls for the duration of the write cycle. When the write to Flash memory is done, the WR bit is cleared automatically.

For protection against accidental operations, the write initiate sequence for NVMKEY must be used to allow any erase or program operation to proceed. After the programming command has been executed, the user must wait for the programming time until programming is complete. The two instructions following the start of the programming sequence should be NOPs, as shown in Example 5-5.

EXAMPLE 5-1: ERASING A PROGRAM MEMORY ROW – ASSEMBLY LANGUAGE CODE

```
; Set up NVMCON for row erase operation
        MOV     #0x4058, W0                 ;
        MOV     W0, NVMCON                  ; Initialize NVMCON
; Init pointer to row to be ERASED
        MOV     #tblpage(PROG_ADDR), W0     ;
        MOV     W0, TBLPAG                  ; Initialize PM Page Boundary SFR
        MOV     #tbloffset(PROG_ADDR), W0   ; Initialize in-page EA[15:0] pointer
        TBLWTL  W0, [W0]                    ; Set base address of erase block
        DISI    #5                          ; Block all interrupts
                                              for next 5 instructions
        MOV     #0x55, W0
        MOV     W0, NVMKEY                  ; Write the 55 key
        MOV     #0xAA, W1                   ;
        MOV     W1, NVMKEY                  ; Write the AA key
        BSET    NVMCON, #WR                 ; Start the erase sequence
        NOP                                 ; Insert two NOPs after the erase
        NOP                                 ; command is asserted
```

6.4.3 READING THE DATA EEPROM

To read a word from data EEPROM, the table read instruction is used. Since the EEPROM array is only 16 bits wide, only the TBLRDL instruction is needed. The read operation is performed by loading TBLPAG and WREG with the address of the EEPROM location, followed by a TBLRDL instruction.

A typical read sequence, using the Table Pointer management (builtin_tblpage and builtin_tbloffset) and table read procedures (builtin_tblrdl) from the C30 compiler library, is provided in Example 6-5.

Program Space Visibility (PSV) can also be used to read locations in the data EEPROM.

EXAMPLE 6-5: READING THE DATA EEPROM USING THE TBLRD COMMAND

```
int __attribute__ ((space(eedata))) eeData = 0x1234;
int data;                                          // Data read from EEPROM
/*-----------------------------------------------------------------------------------------------
The variable eeData must be a Global variable declared outside of any method

the code following this comment can be written inside the method that will execute the read
-----------------------------------------------------------------------------------------------
*/
    unsigned int offset;

    // Set up a pointer to the EEPROM location to be erased
    TBLPAG = __builtin_tblpage(&eeData);               // Initialize EE Data page pointer
    offset = __builtin_tbloffset(&eeData);             // Initizlize lower word of address
    data = __builtin_tblrdl(offset);                   // Write EEPROM data to write latch
```

8.3 Interrupt Control and Status Registers

The PIC24FV32KA304 family of devices implements a total of 23 registers for the interrupt controller:

- INTCON1
- INTCON2
- IFS0, IFS1, IFS3 and IFS4
- IEC0, IEC1, IEC3 and IEC4
- IPC0 through IPC5, IPC7 and IPC15 through IPC19
- INTTREG

Global Interrupt Enable (GIE) control functions are controlled from INTCON1 and INTCON2. INTCON1 contains the Interrupt Nesting Disable (NSTDIS) bit, as well as the control and status flags for the processor trap sources. The INTCON2 register controls the external interrupt request signal behavior and the use of the AIVT.

The IFSx registers maintain all of the interrupt request flags. Each source of interrupt has a status bit, which is set by the respective peripherals, or external signal, and is cleared via software.

The IECx registers maintain all of the interrupt enable bits. These control bits are used to individually enable interrupts from the peripherals or external signals.

The IPCx registers are used to set the Interrupt Priority Level (IPL) for each source of interrupt. Each user interrupt source can be assigned to one of eight priority levels.

The INTTREG register contains the associated interrupt vector number and the new CPU Interrupt Priority Level, which are latched into the Vector Number (VECNUM<6:0>) and the Interrupt Level (ILR<3:0>) bit fields in the INTTREG register. The new Interrupt Priority Level is the priority of the pending interrupt.

The interrupt sources are assigned to the IFSx, IECx and IPCx registers in the same sequence listed in Table 8-2. For example, the INT0 (External Interrupt 0) is depicted as having a vector number and a natural order priority of 0. The INT0IF status bit is found in IFS0<0>, the INT0IE enable bit in IEC0<0> and the INT0IP<2:0> priority bits are in the first position of IPC0 (IPC0<2:0>).

Although they are not specifically part of the interrupt control hardware, two of the CPU Control registers contain bits that control interrupt functionality. The ALU STATUS Register (SR) contains the IPL<2:0> bits (SR<7:5>). These indicate the current CPU Interrupt Priority Level. The user may change the current CPU Interrupt Priority Level by writing to the IPLx bits.

The CORCON register contains the IPL3 bit, which together with IPL<2:0>, also indicates the current CPU Interrupt Priority Level. IPL3 is a read-only bit so that the trap events cannot be masked by the user's software.

All Interrupt registers are described in Register 8-1 through Register 8-33, in the following sections.

REGISTER 8-1: SR: ALU STATUS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R-0, HSC
—	—	—	—	—	—	—	DC(1)
bit 15							bit 8

R/W-0, HSC	R/W-0, HSC	R/W-0, HSC	R-0, HSC	R/W-0, HSC	R/W-0, HSC	R/W-0, HSC	R/W-0, HSC
IPL2(2,3)	IPL1(2,3)	IPL0(2,3)	RA(1)	N(1)	OV(1)	Z(1)	C(1)
bit 7							bit 0

Legend:	HSC = Hardware Settable/Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as '0'

bit 7-5 **IPL<2:0>:** CPU Interrupt Priority Level Status bits(2,3)

111 = CPU Interrupt Priority Level is 7 (15); user interrupts are disabled
110 = CPU Interrupt Priority Level is 6 (14)
101 = CPU Interrupt Priority Level is 5 (13)
100 = CPU Interrupt Priority Level is 4 (12)
011 = CPU Interrupt Priority Level is 3 (11)
010 = CPU Interrupt Priority Level is 2 (10)
001 = CPU Interrupt Priority Level is 1 (9)
000 = CPU Interrupt Priority Level is 0 (8)

Note 1: See Register 3-1 for the description of these bits, which are not dedicated to interrupt control functions.

2: The IPL<2:0> bits are concatenated with the IPL3 bit (CORCON<3>) to form the CPU Interrupt Priority Level. The value in parentheses indicates the Interrupt Priority Level if IPL3 = 1.

3: The IPLx Status bits are read-only when NSTDIS (INTCON1<15>) = 1.

Note: Bit 8 and bits 4 through 0 are described in **Section 3.0 "CPU"**.

REGISTER 8-2: CORCON: CPU CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R/C-0, HSC	R/W-0	U-0	U-0
—	—	—	—	IPL3(2)	PSV(1)	—	—
bit 7							bit 0

Legend:	C = Clearable bit	HSC = Hardware Settable/Clearable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-4 **Unimplemented:** Read as '0'

bit 3 **IPL3:** CPU Interrupt Priority Level Status bit(2)
1 = CPU Interrupt Priority Level is greater than 7
0 = CPU Interrupt Priority Level is 7 or less

bit 1-0 **Unimplemented:** Read as '0'

Note 1: See Register 3-2 for the description of this bit, which is not dedicated to interrupt control functions.
2: The IPL3 bit is concatenated with the IPL<2:0> bits (SR<7:5>) to form the CPU Interrupt Priority Level.

Note: Bit 2 is described in **Section 3.0 "CPU"**.

REGISTER 8-16: IEC5: INTERRUPT ENABLE CONTROL REGISTER 5

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	ULPWUIE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-1 **Unimplemented:** Read as '0'

bit 0 **ULPWUIE:** Ultra Low-Power Wake-up Interrupt Enable Bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

REGISTER 8-19: IPC2: INTERRUPT PRIORITY CONTROL REGISTER 2

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	U1RXIP2	U1RXIP1	U1RXIP0	—	SPI1IP2	SPI1IP1	SPI1IP0
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	SPF1IP2	SPF1IP1	SPF1IP0	—	T3IP2	T3IP1	T3IP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-12 **U1RXIP<2:0>:** UART1 Receiver Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as ‘0’

bit 10-8 **SPI1IP<2:0>:** SPI1 Event Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

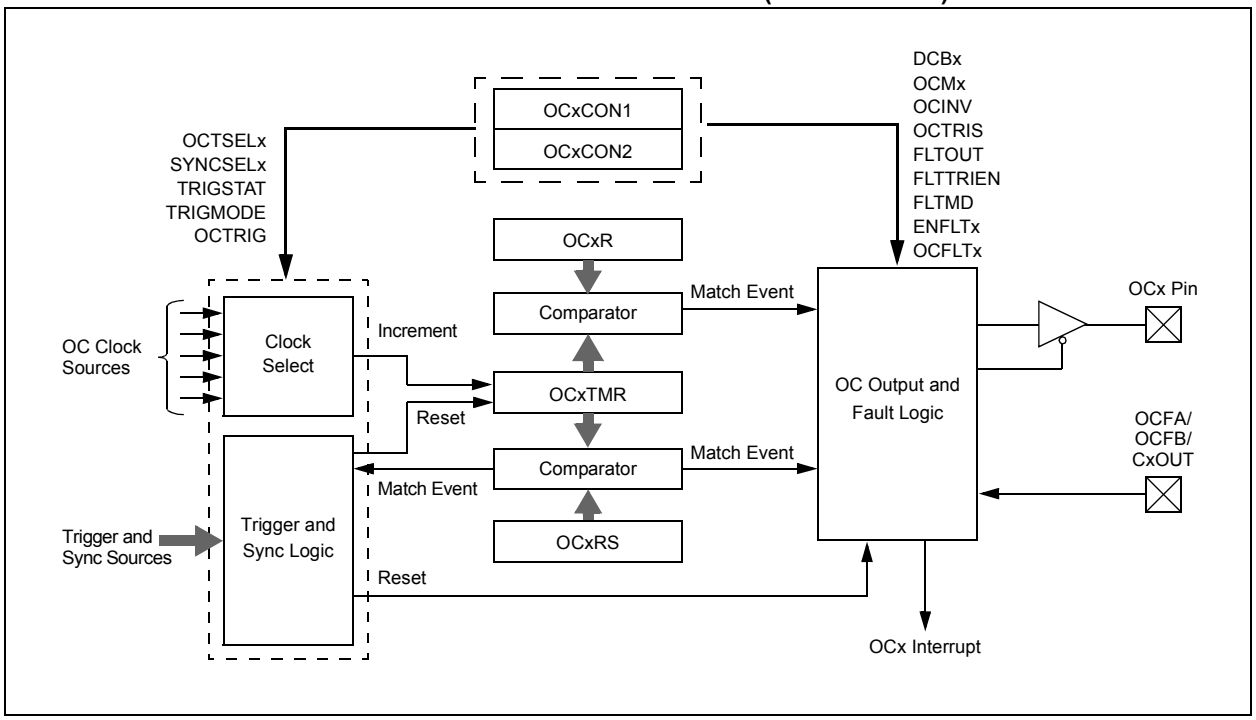
bit 7 **Unimplemented:** Read as ‘0’

bit 6-4 **SPF1IP<2:0>:** SPI1 Fault Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as ‘0’

bit 2-0 **T3IP<2:0>:** Timer3 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

FIGURE 15-1: OUTPUT COMPARE x BLOCK DIAGRAM (16-BIT MODE)



15.4 Subcycle Resolution

The DCBx bits (OCxCON2<10:9>) provide for resolution better than one instruction cycle. When used, they delay the falling edge generated from a match event by a portion of an instruction cycle.

For example, setting DCB<1:0> = 10 causes the falling edge to occur halfway through the instruction cycle in which the match event occurs, instead of at the beginning. These bits cannot be used when OCM<2:0> = 001. When operating the module in PWM mode (OCM<2:0> = 110 or 111), the DCBx bits will be double-buffered.

The DCBx bits are intended for use with a clock source identical to the system clock. When an OCx module with enabled prescaler is used, the falling edge delay caused by the DCBx bits will be referenced to the system clock period, rather than the OCx module's period.

TABLE 15-1: EXAMPLE PWM FREQUENCIES AND RESOLUTIONS AT 4 MIPS (FCY = 4 MHz)(1)

PWM Frequency	7.6 Hz	61 Hz	122 Hz	977 Hz	3.9 kHz	31.3 kHz	125 kHz
Prescaler Ratio	8	1	1	1	1	1	1
Period Value	FFFFh	FFFFh	7FFFh	0FFFh	03FFh	007Fh	001Fh
Resolution (bits)	16	16	15	12	10	7	5

Note 1: Based on FCY = FOSC/2; Doze mode and PLL are disabled.

TABLE 15-2: EXAMPLE PWM FREQUENCIES AND RESOLUTIONS AT 16 MIPS (FCY = 16 MHz)(1)

PWM Frequency	30.5 Hz	244 Hz	488 Hz	3.9 kHz	15.6 kHz	125 kHz	500 kHz
Prescaler Ratio	8	1	1	1	1	1	1
Period Value	FFFFh	FFFFh	7FFFh	0FFFh	03FFh	007Fh	001Fh
Resolution (bits)	16	16	15	12	10	7	5

Note 1: Based on FCY = FOSC/2; Doze mode and PLL are disabled.

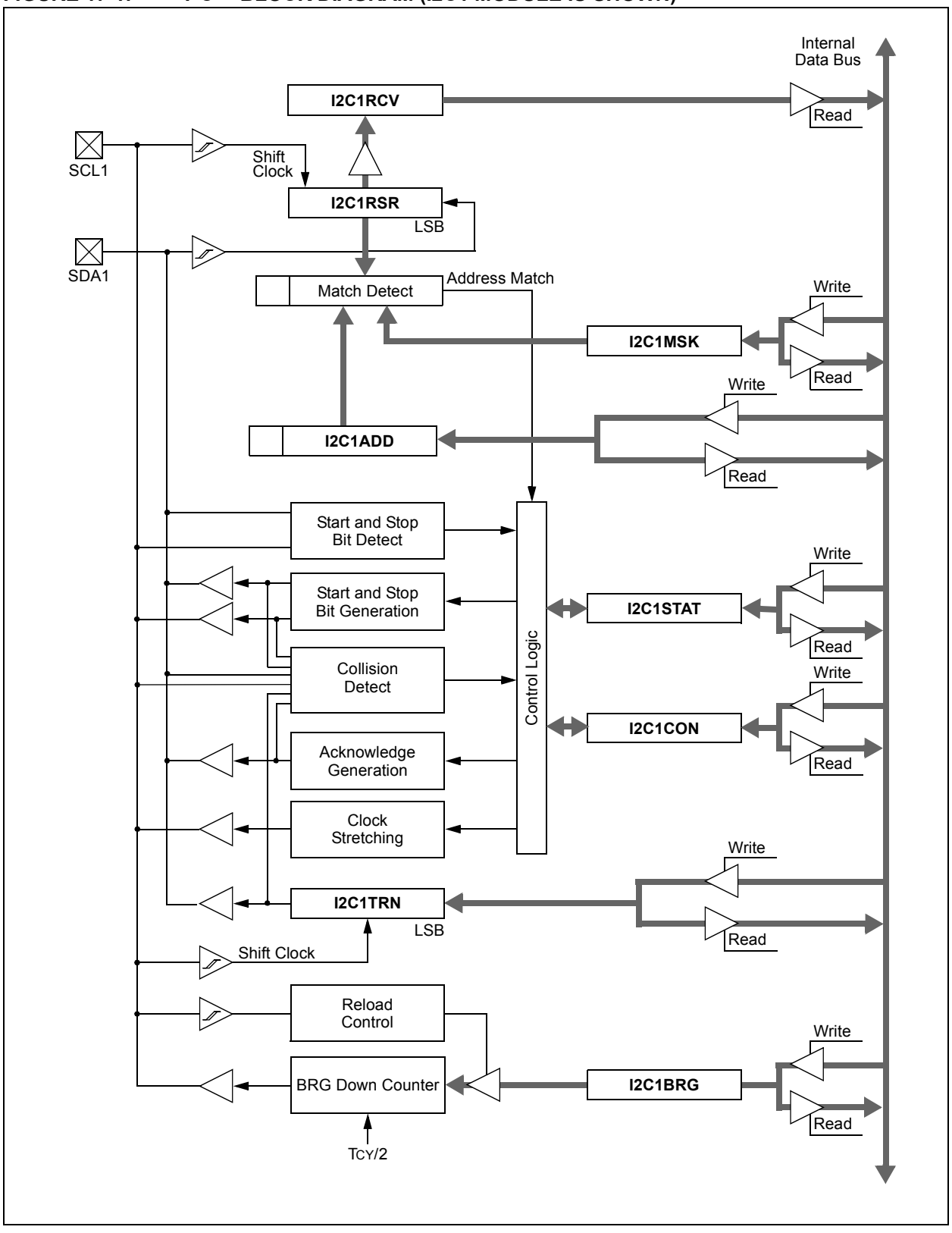
REGISTER 15-1: OCxCON1: OUTPUT COMPARE x CONTROL REGISTER 1 (CONTINUED)

bit 2-0 **OCM<2:0>:** Output Compare x Mode Select bits(1)

111 = Center-Aligned PWM mode on OCx
110 = Edge-Aligned PWM mode on OCx
101 = Double Compare Continuous Pulse mode: Initialize OCx pin low; toggle OCx state continuously on alternate matches of OCxR and OCxRS
100 = Double Compare Single-Shot mode: Initialize OCx pin low; toggle OCx state on matches of OCxR and OCxRS for one cycle
011 = Single Compare Continuous Pulse mode: Compare events continuously toggle the OCx pin
010 = Single Compare Single-Shot mode: Initialize OCx pin high; compare event forces the OCx pin low
001 = Single Compare Single-Shot mode: Initialize OCx pin low, compare event forces the OCx pin high
000 = Output compare channel is disabled

Note 1: The comparator module used for Fault input varies with the OCx module. OC1 and OC2 use Comparator 1; OC3 and OC4 use Comparator 2; OC5 uses Comparator 3.

FIGURE 17-1: I²C™ BLOCK DIAGRAM (I2C1 MODULE IS SHOWN)



REGISTER 22-4: AD1CON5: A/D CONTROL REGISTER 5

R/W-0	R/W-0	R/W-0	R/W-0	r-0	U-0	R/W-0	R/W-0
ASEN(1)	LPEN	CTMREQ	BGREQ	r	—	ASINT1	ASINT0
bit 15							bit 8

U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	—	WM1	WM0	CM1	CM0
bit 7							bit 0

Legend:	r = Reserved bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ASEN:** Auto-Scan Enable bit(1)
- 1 = Auto-scan is enabled
- 0 = Auto-scan is disabled

bit 14 **LPEN:** Low-Power Enable bit
- 1 = Returns to Low-Power mode after scan
- 0 = Remains in Full-Power mode after scan

bit 13 **CTMREQ:** CTMU Request bit
- 1 = CTMU is enabled when the A/D is enabled and active
- 0 = CTMU is not enabled by the A/D

bit 12 **BGREQ:** Band Gap Request bit
- 1 = Band gap is enabled when the A/D is enabled and active
- 0 = Band gap is not enabled by the A/D

bit 11 **Reserved:** Maintain as '0'

bit 10 **Unimplemented:** Read as '0'

bit 9-8 **ASINT<1:0>:** Auto-Scan (Threshold Detect) Interrupt Mode bits
- 11 = Interrupt after a Threshold Detect sequence completed and a valid compare has occurred
- 10 = Interrupt after a valid compare has occurred
- 01 = Interrupt after a Threshold Detect sequence completed
- 00 = No interrupt

bit 7-4 **Unimplemented:** Read as '0'

bit 3-2 **WM<1:0>:** Write Mode bits
- 11 = Reserved
- 10 = Auto-compare only (conversion results are not saved, but interrupts are generated when a valid match, as defined by the CMx and ASINTx bits, occurs)
- 01 = Convert and save (conversion results are saved to locations as determined by the register bits when a match, as defined by the CMx bits, occurs)
- 00 = Legacy operation (conversion data is saved to a location determined by the buffer register bits)

bit 1-0 **CM<1:0>:** Compare Mode bits
- 11 = Outside Window mode (valid match occurs if the conversion result is outside of the window defined by the corresponding buffer pair)
- 10 = Inside Window mode (valid match occurs if the conversion result is inside the window defined by the corresponding buffer pair)
- 01 = Greater Than mode (valid match occurs if the result is greater than the value in the corresponding buffer register)
- 00 = Less Than mode (valid match occurs if the result is less than the value in the corresponding buffer register)

Note 1: When using auto-scan with Threshold Detect (ASEN = 1), do not configure the sample clock source to Auto-Convert mode (SSRCx = 7). Any other available SSRCx selection is valid. To use auto-convert as the sample clock source (SSRCx = 7), make sure ASEN is cleared.

REGISTER 22-5: AD1CHS: A/D SAMPLE SELECT REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CH0NB2	CH0NB1	CH0NB0	CH0SB4	CH0SB3	CH0SB2	CH0SB1	CH0SB0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CH0NA2	CH0NA1	CH0NA0	CH0SA4	CH0SA3	CH0SA2	CH0SA1	CH0SA0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **CH0NB<2:0>:** Sample B Channel 0 Negative Input Select bits
111 = AN6(1)
110 = AN5(2)
101 = AN4
100 = AN3
011 = AN2
010 = AN1
001 = AN0
000 = AVSS

bit 12-8 **CH0SB<4:0>:** S/H Amplifier Positive Input Select for MUX B Multiplexer Setting bits
11111 = Unimplemented, do not use
11110 = AVDD
11101 = AVSS
11100 = Upper guardband rail (0.785 * VDD)
11011 = Lower guardband rail (0.215 * VDD)
11010 = Internal Band Gap Reference (VBG)(3)
11001-10010 = Unimplemented, do not use
10001 = No channels are connected, all inputs are floating (used for CTMU)
10000 = No channels are connected, all inputs are floating (used for CTMU temperature sensor input)
01111 = AN15
01110 = AN14
01101 = AN13
01100 = AN12
01011 = AN11
01010 = AN10
01001 = AN9
01000 = AN8(1)
00111 = AN7(1)
00110 = AN6(1)
00101 = AN5(2)
00100 = AN4
00011 = AN3
00010 = AN2
00001 = AN1
00000 = AN0

bit 7-5 **CH0NA<2:0>:** Sample A Channel 0 Negative Input Select bits
The same definitions as for CHONB<2:0>.

bit 4-0 **CH0SA<4:0>:** Sample A Channel 0 Positive Input Select bits
The same definitions as for CHONA<4:0>.

Note 1: This is implemented on 44-pin devices only.
2: This is implemented on 28-pin and 44-pin devices only.
3: The band gap value used for this input is 2x or 4x the internal VBG, which is selected when PVCFG<1:0> = 1x.

TABLE 29-4: HIGH/LOW–VOLTAGE DETECT CHARACTERISTICS

Standard Operating Conditions: 1.8V to 3.6V PIC24F32KA3XX 2.0V to 5.5V PIC24FV32KA3XX Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended								
Param No.	**Symbol**	**Characteristic**		**Min**	**Typ**	**Max**	**Units**	**Conditions**
DC18	VHLVD	HLVD Voltage on VDD Transition	HLVDL<3:0> = 0000(2)	—	—	1.90	V	
			HLVDL<3:0> = 0001	1.86	—	2.13	V	
			HLVDL<3:0> = 0010	2.08	—	2.35	V	
			HLVDL<3:0> = 0011	2.22	—	2.53	V	
			HLVDL<3:0> = 0100	2.30	—	2.62	V	
			HLVDL<3:0> = 0101	2.49	—	2.84	V	
			HLVDL<3:0> = 0110	2.73	—	3.10	V	
			HLVDL<3:0> = 0111	2.86	—	3.25	V	
			HLVDL<3:0> = 1000	3.00	—	3.41	V	
			HLVDL<3:0> = 1001	3.16	—	3.59	V	
			HLVDL<3:0> = 1010(1)	3.33	—	3.79	V	
			HLVDL<3:0> = 1011(1)	3.53	—	4.01	V	
			HLVDL<3:0> = 1100(1)	3.74	—	4.26	V	
			HLVDL<3:0> = 1101(1)	4.00	—	4.55	V	
			HLVDL<3:0> = 1110(1)	4.28	—	4.87	V	

Note 1: These trip points should not be used on PIC24FXXKA30X devices.

2: This trip point should not be used on PIC24FVXXKA30X devices.

TABLE 29-5: BOR TRIP POINTS

Standard Operating Conditions: 1.8V to 3.6V PIC24F32KA3XX 2.0V to 5.5V PIC24FV32KA3XX Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended								
Param No.	**Sym**	**Characteristic**		**Min**	**Typ**	**Max**	**Units**	**Conditions**
DC15		BOR Hysteresis		—	5	—	mV	
DC19		BOR Voltage on VDD Transition	BORV<1:0> = 00	—	—	—	—	Valid for LPBOR and DSBOR (**Note 1)**
			BORV<1:0> = 01	2.90	3	3.38	V	
			BORV<1:0> = 10	2.53	2.7	3.07	V	
			BORV<1:0> = 11	1.75	1.85	2.05	V	**(Note 2)**
			BORV<1:0> = 11	1.95	2.05	2.16	V	**(Note 3)**

Note 1: LPBOR re-arms the POR circuit but does not cause a BOR.

2: This is valid for PIC24F (3.3V) devices.

3: This is valid for PIC24FV (5V) devices.

TABLE 29-8: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD)

DC CHARACTERISTICS		Standard Operating Conditions: 1.8V to 3.6V PIC24F32KA3XX 2.0V to 5.5V PIC24FV32KA3XX Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Parameter No.	**Device**	**Typical(1)**	**Max**	**Units**	**Conditions**		
Power-Down Current (IPD)							
DC60	PIC24FV32KA3XX	6.0	—	µA	-40°C	2.0V	Sleep Mode(2)
			8.0		+25°C		
			8.5		+60°C		
			9.0		+85°C		
		—	15		+125°C		
		6.0	—	µA	-40°C	5.0V	
			8.0		+25°C		
			9.0		+60°C		
			10.0		+85°C		
		—	15		+125°C		
	PIC24F32KA3XX	0.025	—	µA	-40°C	1.8V	
			0.80		+25°C		
			1.5		+60°C		
			2.0		+85°C		
		—	7.5		+125°C		
		0.040	—	µA	-40°C	3.3V	
			1.0		+25°C		
			2.0		+60°C		
			3.0		+85°C		
		—	7.5		+125°C		
DC61	PIC24FV32KA3XX	0.25	—	µA	-40°C	2.0V	Low-Voltage Sleep Mode(2)
		0.35	3.0	µA	+85°C	5.0V	
		—	7.5	µA	+125°C	5.0V	
DC70	PIC24FV32KA3XX	0.03	—	µA	-40°C	2.0V	Deep Sleep Mode
		0.10	2.0	µA	+85°C	5.0V	
		—	6.0	µA	+125°C	5.0V	
	PIC24F32KA3XX	0.02	—	µA	-40°C	1.8V	
		0.08	1.2	µA	+85°C	3.3V	
		—	1.2	µA	+125°C	3.3V	

Legend: Unshaded rows represent PIC24F32KA3XX devices and shaded rows represent PIC24FV32KA3XX devices.

Note 1: Data in the Typical column is at 3.3V, +25°C (PIC24F32KA3XX) or 5.0V, +25°C (PIC24FV32KA3XX) unless otherwise stated. Parameters are for design guidance only and are not tested.

2: Base IPD is measured with all peripherals and clocks shut down. All I/Os are configured as outputs and set low, PMSLP is set to '0' and WDT, etc., are all switched off.

3: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base IPD current.

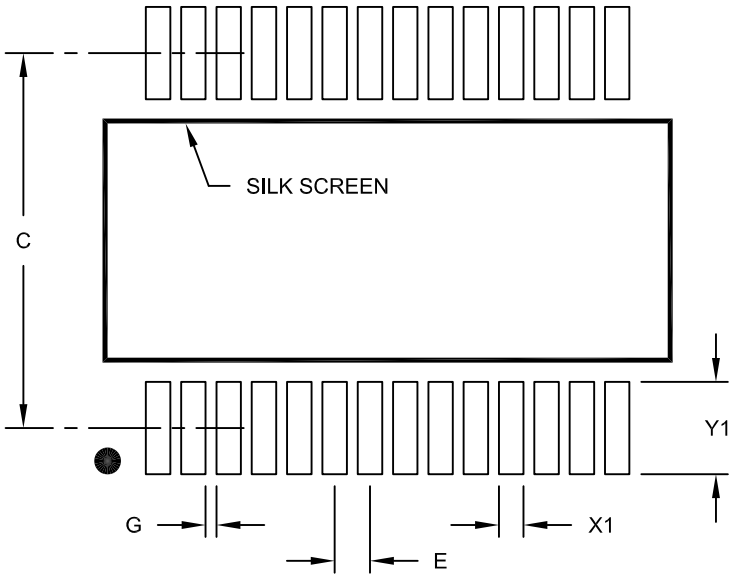
4: This current applies to Sleep only.

5: This current applies to Sleep and Deep Sleep.

6: This current applies to Deep Sleep only.

28-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C		7.20	
Contact Pad Width (X28)	X1			0.45
Contact Pad Length (X28)	Y1			1.75
Distance Between Pads	G	0.20		

Notes:

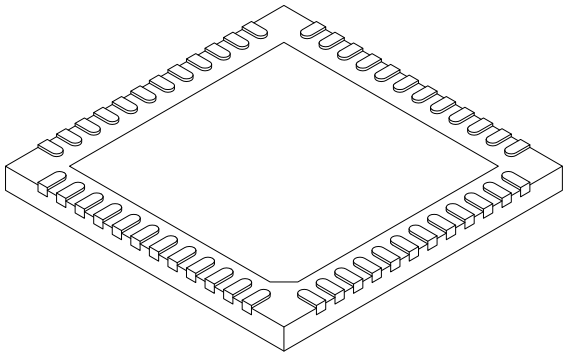
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2073A

48-Lead Plastic Ultra Thin Quad Flat, No Lead Package (MV) – 6x6x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		48	
Pitch	e		0.40 BSC	
Overall Height	A	0.45	0.50	0.55
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.127 REF	
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	4.45	4.60	4.75
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	4.45	4.60	4.75
Contact Width	b	0.15	0.20	0.25
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-153A Sheet 2 of 2